SCBS157F - JANUARY 1991 - REVISED MAY 1997

- State-of-the-Art *EPIC-IIB™* BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Typical VOLP (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- **Package Options Include Plastic** Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs

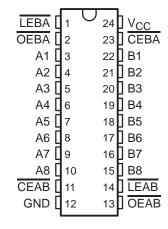
description

The 'ABT543A octal transceivers contain two sets of D-type latches for temporary storage of data flowing in either direction. Separate latch-enable (LEAB or LEBA) and output-enable (OEAB or OEBA) inputs are provided for each register to permit independent control in either direction of data flow.

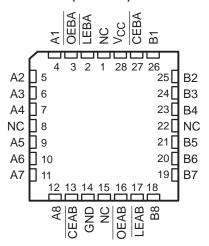
The A-to-B enable (CEAB) input must be low to enter data from A or to output data from B. If CEAB is low and \overline{LEAB} is low, the A-to-B latches are transparent; a subsequent low-to-high transition of LEAB puts the A latches in the storage mode. With CEAB and OEAB both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar, but requires using the CEBA, LEBA, and OEBA inputs.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN54ABT543A . . . JT OR W PACKAGE SN74ABT543A...DB, DW, NT, OR PW PACKAGE (TOP VIEW)



SN54ABT543A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The SN54ABT543A is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT543A is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated



SN54ABT543A, SN74ABT543A OCTAL REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

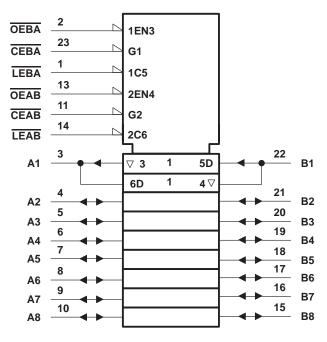
SCBS157F - JANUARY 1991 - REVISED MAY 1997

FUNCTION TABLE†

	INPUTS								
CEAB	LEAB	OEAB	Α	В					
Н	Х	Х	Χ	Z					
Х	X	Н	Χ	Z					
L	Н	L	Χ	в ₀ ‡					
L	L	L	L	L					
L	L	L	Н	Н					

[†] A-to-B data flow is shown; B-to-A flow control is the same except that it uses CEBA, LEBA, and OEBA.

logic symbol§

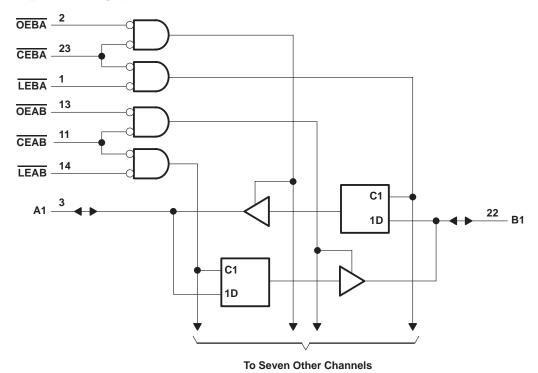


§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.



[‡]Output level before the indicated steady-state input conditions were established

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	\dots -0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V _O	–0.5 V to 5.5 V
Current into any output in the low state, I _O : SN54ABT543A	96 mA
SN74ABT543A	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	
Package thermal impedance, θ _{JA} (see Note 2): DB package	
DW package	
NT package	67°C/W
PW package	
Storage temperature range, T _{sto}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.



SN54ABT543A, **SN74ABT543A** OCTAL REGISTERED TRANSCEIVERS **WITH 3-STATE OUTPUTS**

SCBS157F - JANUARY 1991 - REVISED MAY 1997

recommended operating conditions (see Note 3)

			SN54AB	T543A	SN74AB	T543A	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2		2		V
VIL	Low-level input voltage			0.8		0.8	V
٧ _I	Input voltage		0	VCC	0	VCC	V
ЮН	High-level output current			-24		-32	mA
loL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
TA	Operating free-air temperature		- 55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			NETIONS	Т	A = 25°C	;	SN54AB	T543A	SN74AB	T543A		
PAI	RAMETER	l lesi co	NDITIONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNIT	
VIK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
\ \/ a		V _{CC} = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3		V	
VOH		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				V	
		vCC = 4.5 v	$I_{OH} = -32 \text{ mA}$	2*					2			
Voi		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V	
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V	
V _{hys}					100						mV	
١.	Control inputs	V00 - 5 5 V	V1 - V20 or CND			±1		±1		±1		
tį	A or B ports	V _{CC} = 5.5 V,	$V_I = V_{CC}$ or GND			±100		±100		±100	μΑ	
lozH [‡]		$V_{CC} = 5.5 \text{ V},$	V _O = 2.7 V			10§		10§		10§	μΑ	
l _{OZL} ‡		$V_{CC} = 5.5 V,$	V _O = 0.5 V			-10§		-10§		-10§	μΑ	
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ	
IOI		V _{CC} = 5.5 V,	V _O = 2.5 V	-50*	-100	-180*	-50	-200	-50	-180	mA	
		V _{CC} = 5.5 V,	Outputs high		1	250*		350		250	μΑ	
Icc	A or B ports	$I_{O} = 0$,	Outputs low		24	30*		34		30	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled		0.5	250*		350		250	μΑ	
∆lcc#		V _{CC} = 5.5 V, One in Other inputs at V _{CC}				1.5		1.5		1.5	mA	
Ci	Control inputs	V _I = 2.5 V or 0.5 V			4						pF	
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V			7						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.



[†] All typical values are at V_{CC} = 5 V. ‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.

[§] This data sheet limit may vary among suppliers.

 $[\]P$ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 $^{^{\#}}$ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SCBS157F - JANUARY 1991 - REVISED MAY 1997

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

					SN54AE	3T543A		
				V _{CC} :	= 5 V, 25°C	MIN	MAX	UNIT
				MIN	MAX			
t _W	Pulse duration, LEAB or LEBA low			3.5		3.5		ns
		Data before LEAB or LEBA↑	High	2.5		2.5		
١.	Setup time	Data before LEAB of LEBA	Low	3		3		ns
t _{su}	Setup time	Data before CEAB or CEBA↑	High	2.5		2.5		115
		Data before CEAB or CEBA	Low	3		3		
4.	Hold time	Data after LEAB or LEBA↑				1		no
th	riola time	Data after CEAB or CEBA↑		1		1		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

					SN74AE	3T543A		
				V _{CC} =	= 5 V, 25°C	MIN	MAX	UNIT
				MIN	MAX			
t _W	Pulse duration, LEAB or LEBA low			3.5		3.5		ns
		Data before <u>LEAB</u> or <u>LEBA</u> ↑	High	3.5		3.5		
	Setup time	Data before LEAB of LEBA	Low	3		3		ns
t _{su}	Setup time	Data before CEAB or CEBA↑	High	3.5		3.5		115
		Data before CEAB of CEBA	Low	3		3		
+.	Hold time	Data after LEAB or LEBA↑	0.5		0.5		ns	
th	riold time	Data after CEAB or CEBA↑		0.5		0.5		115

SN54ABT543A, SN74ABT543A OCTAL REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS157F - JANUARY 1991 - REVISED MAY 1997

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

				SN5	4ABT54	3A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C	CC = 5 V A = 25°C	', ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
t _{PLH}	A or B	B or A	1.6†	4.4	4.4	1.6†	5.5	ns
t _{PHL}	AOIB	BULK	1.6	4.4	5.1	1.6	6.2	115
tPLH	LEBA or LEAB	A or B	1.6†	4.1	5.1	1.6†	6.6	ns
t _{PHL}	LEDA OI LEAD	AOID	1.6	4.6	5.4	1.6	6.4	115
^t PZH	OEBA or OEAB	A or B	1.4	3.9	4.1	1.4	5.1	ns
tPZL	OEBA OF OEAB	AUID	2	5	4.9	2	5.8	115
^t PHZ	OEBA or OEAB	A or B	2.5†	5.9	5.8	2.5†	6.9	ns
t _{PLZ}	OEDA OI OEAD	AOID	2.5†	5.5	6.1	2.5†	7.6	115
^t PZH	CEBA or CEAB	A or B	1.4	3.9	4.7	1.4	5.6	20
tPZL	CEDA OF CEAB	A UI D	2	5	5.7	2	6.2	ns
^t PHZ	CEBA or CEAB	A or B	3.2†	5.9	6.5	3.2†	7.3	—l ns l
t _{PLZ}	OLDA OF CEAD	AUID	2.5†	5.5	6.7	2.5†	7.8	

[†] This data sheet limit may vary among suppliers.

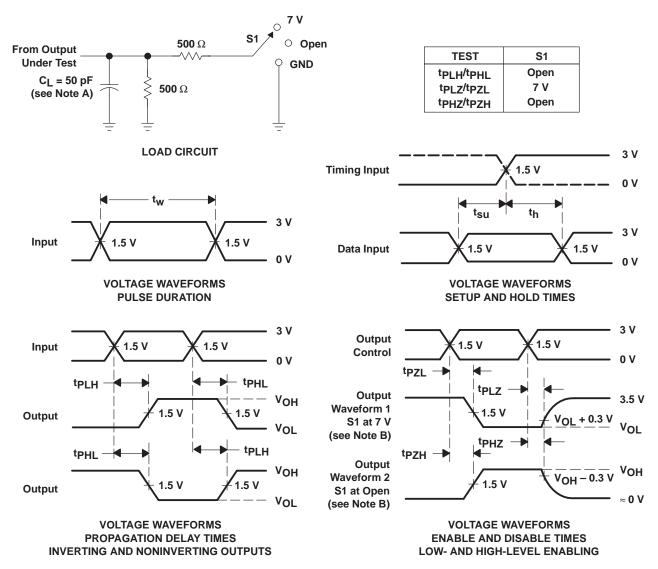
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

				SN7	4ABT54	3A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)		CC = 5 V 4 = 25°C		MIN	MAX	UNIT
			MIN	TYP	MAX			
^t PLH	A or B	B or A	1.8†	4.4	5.9	1.8†	6.9	ns
^t PHL	AOIB	BULK	1.9	4.4	5.9	1.9	6.9	115
tPLH	LEBA or LEAB	A or B	1.5†	4.1	5.6	1.5†	6.6	ns
^t PHL	LEDA OI LEAD	AOIB	2.1	4.6	6.1	2.1	7.1	113
^t PZH	OEBA or OEAB	A or B	1.4	3.9	5.4	1.4	6.4	ns
t _{PZL}	OEBA OI OEAB	AOID	2.5	5	6.5	2.5	7.5	115
t _{PHZ}	OEBA or OEAB	A or B	2.5†	5.9	7.4	2.5†	8.4	ns
t _{PLZ}	OEBA OI OEAB	AOIB	2.5†	5.5	7	2.5†	8	115
^t PZH	CEBA or CEAB	A or B	1.4	3.9	5.4	1.4	6.4	ns
t _{PZL}	CEDA OF CEAB	AUID	2.5	5	6.5	2.5	7.5	115
^t PHZ	CEBA or CEAB	A or B	2.9†	5.9	7.4	2.9†	8.4	— ns l
^t PLZ	OLDA OF CLAB	AUIB	2.4†	5.5	7	2.4†	8	

[†]This data sheet limit may vary among suppliers.



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

www.ti.com 23-Nov-2025

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-9231402Q3A	Active	Production	LCCC (FK) 28	42 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9231402Q3A SNJ54 ABT543AFK
SN74ABT543ADBR	Active	Production	SSOP (DB) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A
SN74ABT543ADBR.B	Active	Production	SSOP (DB) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A
SN74ABT543ADBRG4	Active	Production	SSOP (DB) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A
SN74ABT543ADW	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT543A
SN74ABT543ADW.B	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT543A
SN74ABT543ADWR	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT543A
SN74ABT543ADWR.B	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT543A
SN74ABT543ADWRG4	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT543A
SN74ABT543ADWRG4.B	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT543A
SN74ABT543APW	Active	Production	TSSOP (PW) 24	60 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A
SN74ABT543APW.B	Active	Production	TSSOP (PW) 24	60 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A
SN74ABT543APWR	Active	Production	TSSOP (PW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A
SN74ABT543APWR.B	Active	Production	TSSOP (PW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A
SNJ54ABT543AFK	Active	Production	LCCC (FK) 28	42 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9231402Q3A SNJ54 ABT543AFK

⁽¹⁾ Status: For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

PACKAGE OPTION ADDENDUM

www.ti.com 23-Nov-2025

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54ABT543A, SN74ABT543A:

Catalog: SN74ABT543A

Military: SN54ABT543A

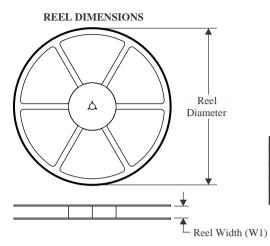
NOTE: Qualified Version Definitions:

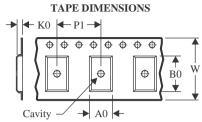
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 9-Oct-2025

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

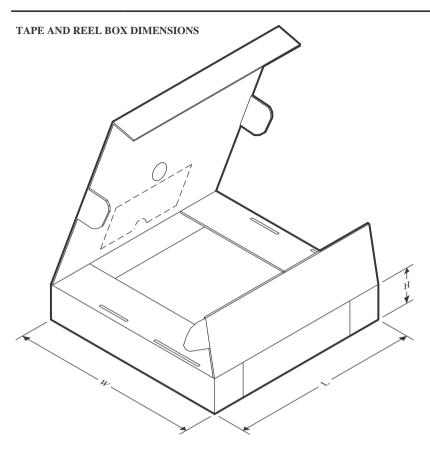
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT543ADBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
SN74ABT543ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74ABT543ADWRG4	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74ABT543APWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

www.ti.com 9-Oct-2025



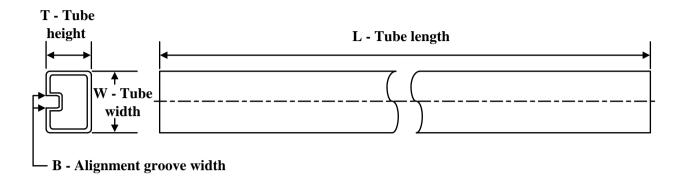
*All dimensions are nominal

7 till dillitorioriorio di o ricirilitati							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT543ADBR	SSOP	DB	24	2000	353.0	353.0	32.0
SN74ABT543ADWR	SOIC	DW	24	2000	350.0	350.0	43.0
SN74ABT543ADWRG4	SOIC	DW	24	2000	350.0	350.0	43.0
SN74ABT543APWR	TSSOP	PW	24	2000	353.0	353.0	32.0

PACKAGE MATERIALS INFORMATION

www.ti.com 9-Oct-2025

TUBE

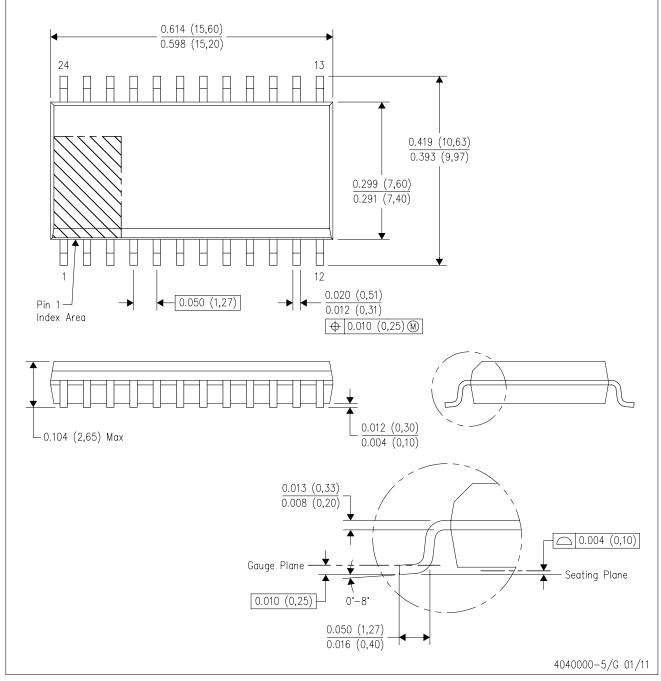


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABT543ADW	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN74ABT543ADW.B	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN74ABT543APW	PW	TSSOP	24	60	530	10.2	3600	3.5
SN74ABT543APW.B	PW	TSSOP	24	60	530	10.2	3600	3.5

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



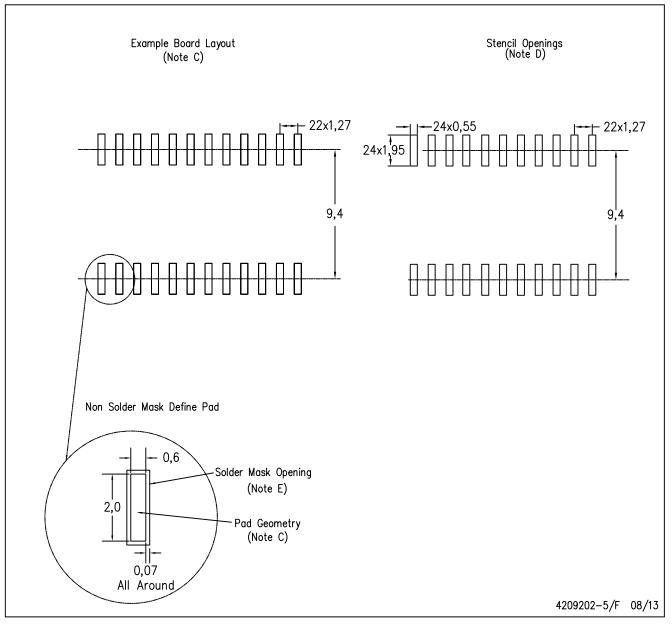
NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

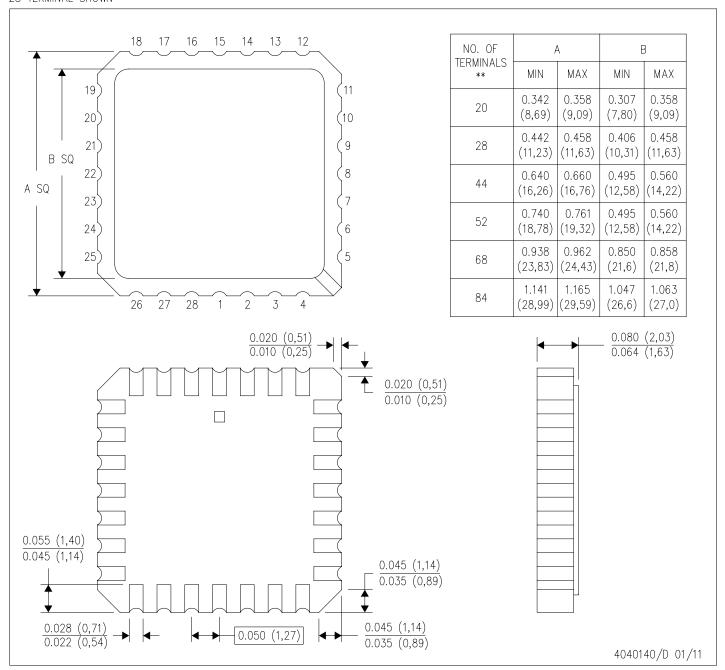
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



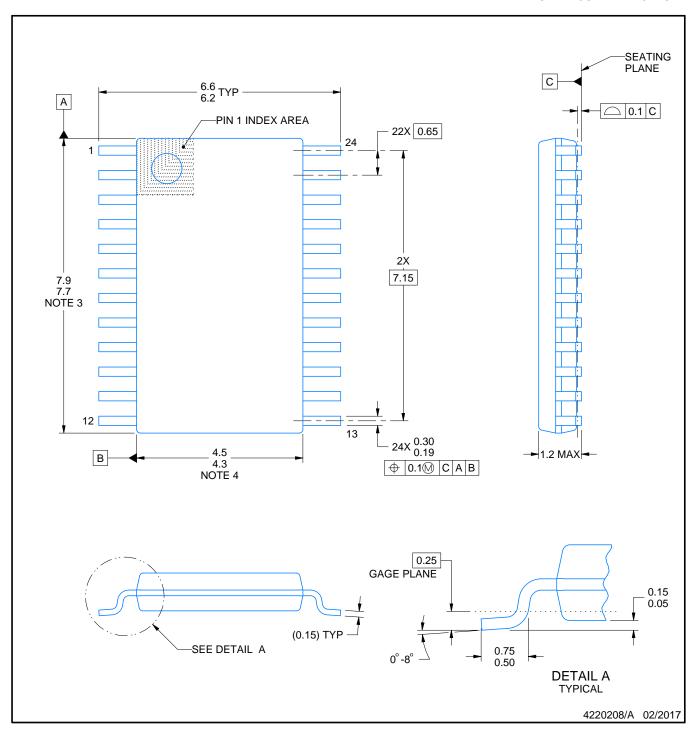
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004





SMALL OUTLINE PACKAGE



NOTES:

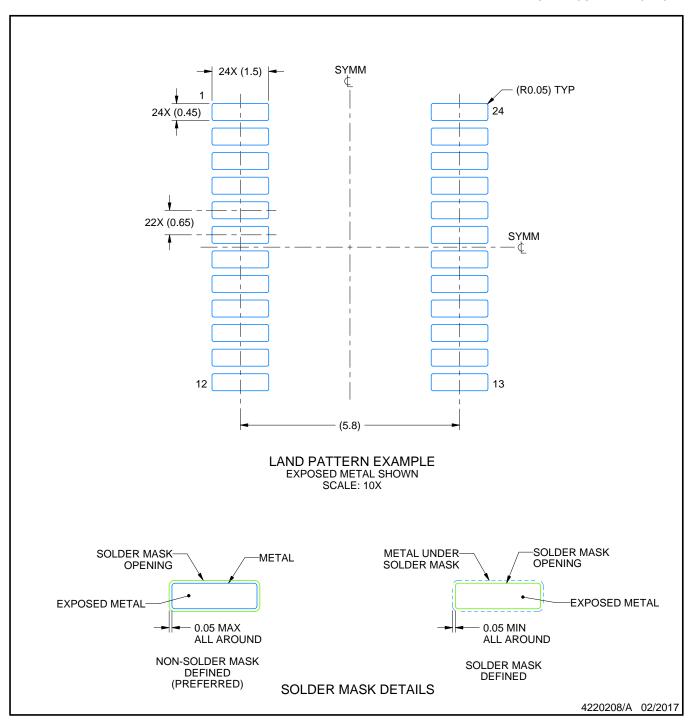
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



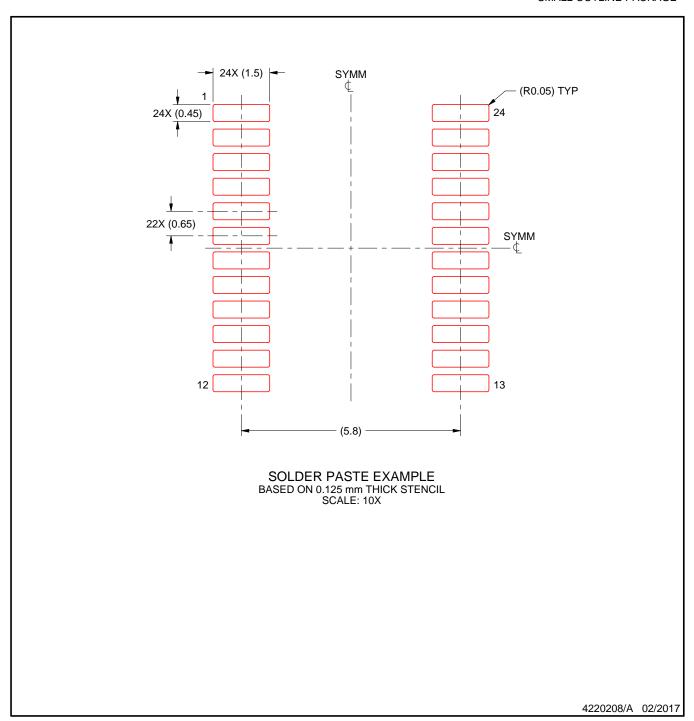
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale, TI's General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025